

# Surface Mount Schottky Power Rectifier

## MBRS130T3G, NRVBS130T3G, NRVBS130N

This device employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system.

### Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Very Low Forward Voltage Drop (0.6 Volts Max @ 1.0 A,  $T_j = 25^\circ\text{C}$ )
- Excellent Ability to Withstand Reverse Avalanche Energy Transients
- Guardring for Stress Protection
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable\*
- These are Pb-Free Devices

### Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 95 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes:  $260^\circ\text{C}$  Max. for 10 Seconds
- Shipped in 12 mm Tape and Reel, 2500 units per reel
- Cathode Polarity Band



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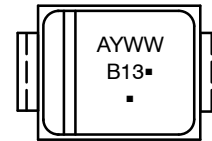
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## SCHOTTKY BARRIER RECTIFIER 1.0 AMPERE 30 VOLTS



SMB  
CASE 403A

### MARKING DIAGRAM



- A = Assembly Location\*\*
- Y = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*\*The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

### ORDERING INFORMATION

Device	Package	Shipping†
MBRS130T3G	SMB (Pb-Free)	2500 / Tape & Reel
NRVBS130T3G*	SMB (Pb-Free)	2500 / Tape & Reel
NRVBS130NT3G*	SMB (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MBRS130T3G, NRVBS130T3G, NRVBS130N

## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	30	V
Average Rectified Forward Current ( $T_L = 115^\circ\text{C}$ )	$I_{F(AV)}$	1.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	40	A
Operating Junction Temperature	$T_J$	-65 to +125	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead ( $T_L = 25^\circ\text{C}$ )	$R_{\theta JL}$	12	$^\circ\text{C/W}$

## ELECTRICAL CHARACTERISTICS

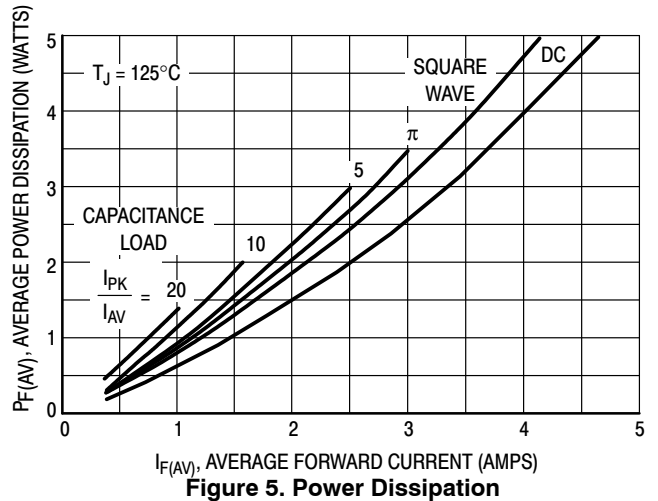
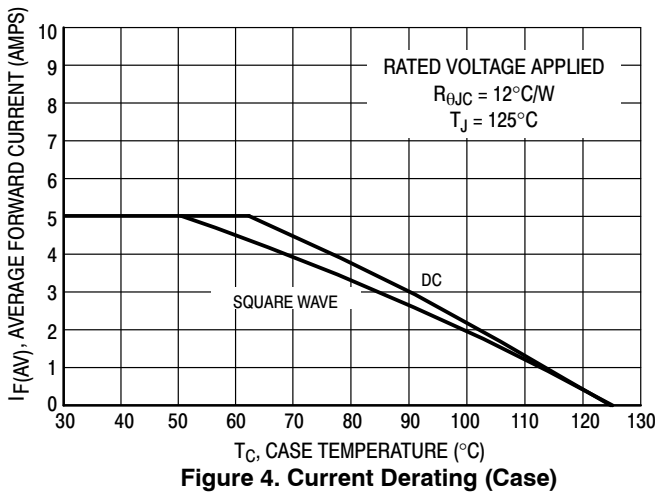
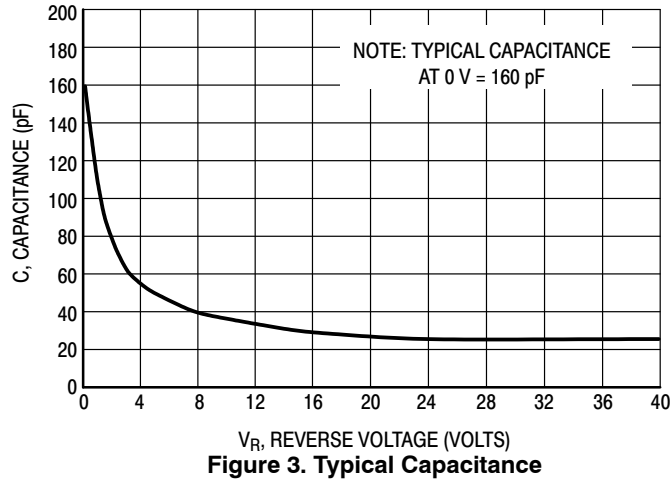
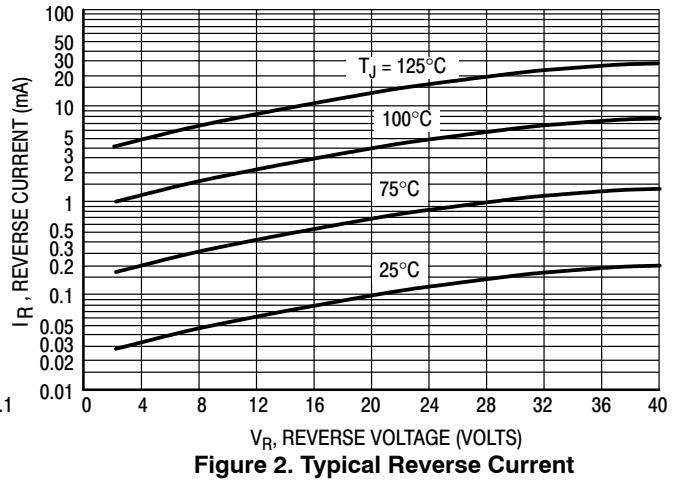
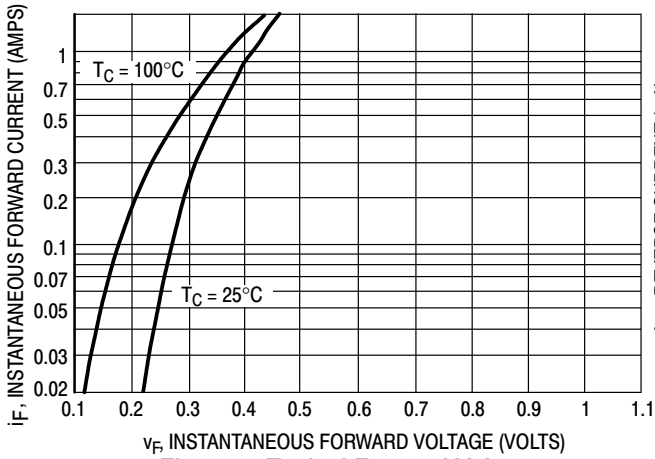
Rating	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 1) ( $i_F = 1.0\text{ A}$ , $T_J = 25^\circ\text{C}$ )	$V_F$	0.6	V
Maximum Instantaneous Reverse Current (Note 1) (Rated dc Voltage, $T_J = 25^\circ\text{C}$ ) (Rated dc Voltage, $T_J = 100^\circ\text{C}$ )	$i_R$	1.0 10	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

# MBRS130T3G, NRVBS130T3G, NRVBS130N

## TYPICAL CHARACTERISTICS



# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

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SCALE 1:1

Polarity Band



SCALE 1:1

Non-Polarity Band

**SMB**  
CASE 403A-03  
ISSUE J

DATE 19 JUL 2012

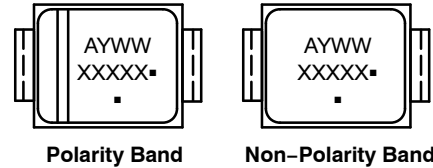


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.95	2.30	2.47	0.077	0.091	0.097
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
c	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1	0.51 REF			0.020 REF		

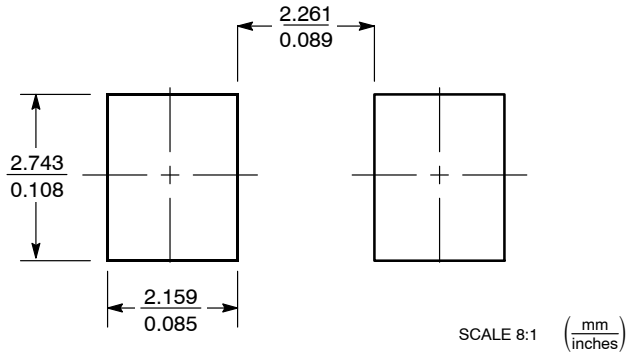
**GENERIC MARKING DIAGRAM\***



- XXXXX = Specific Device Code
  - A = Assembly Location
  - Y = Year
  - WW = Work Week
  - = Pb-Free Package
- (Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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